1. (Currently Amended) A testing method for testing ~~contacting~~ electrical coupling between a semiconductor ~~chip~~ device and a test carrier, comprising:

loading the test carrier with the semiconductor ~~chip~~ device such that contacts of the semiconductor ~~chip~~ device directly contact corresponding contacts of the test carrier,

wherein the ~~contacting~~ electrical coupling between the test carrier and the semiconductor ~~chip~~ device is tested immediately after the loading of the test carrier with the semiconductor ~~chip,~~ device; and

wherein the semiconductor ~~chip~~ device comprises one or more exclusive ~~contacting~~ test contacts ~~exclusively~~ for testing the ~~contacting~~ electrical coupling between the semiconductor ~~chip~~ device and the test ~~carrier immediately after the loading of the test carrier with the semiconductor chip.~~ carrier; and

unloading the semiconductor device from the test carrier based on a criterion, wherein the criterion is based on the electrical coupling between the test carrier and the semiconductor device obtained from the test.

2. (Original) The testing method according to claim 1, further comprising connecting the carrier to a testing apparatus.

3. (Currently Amended) The testing method according to claim 2, wherein the carrier is connected to the testing apparatus, and the carrier is subsequently loaded with the semiconductor ~~chip.~~ device.

4. (Currently Amended) The testing method according to claim 1, wherein the carrier is loaded at a carrier loading station, and the ~~contacting~~ electrical coupling

between the carrier and the semiconductor ~~chip~~ device is tested before the carrier is transported to a further testing station.

5. (Currently Amended) The testing method according to claim 2, wherein the ~~contacting~~ electrical coupling between the carrier and the semiconductor ~~chip~~ device is tested by the testing apparatus.

6. (Currently Amended) The testing method according to claim 5, wherein the testing apparatus is configured such that it tests the ~~contacting~~ electrical coupling between the carrier and the semiconductor ~~chip,~~ device, but not functioning of the semiconductor ~~chip.~~ device.

7. (Currently Amended) The testing method according to claim 1, wherein the ~~contacting~~ electrical coupling between the carrier and the semiconductor ~~chip~~ device is tested less than 2 seconds after loading of the carrier with the semiconductor ~~chip~~ device.

8. (Currently Amended) The testing method according to claim 1, further comprising determining during the testing of the ~~contacting~~ electrical coupling between the carrier and the semiconductor ~~chip~~ device whether an ~~electric~~ electrical contact has been established between a ~~corresponding pad~~ test contact of the semiconductor ~~chip~~ device and an assigned pad of the carrier after loading of the carrier with the semiconductor ~~chip~~ device.

9. (Currently Amended) The testing method according to claim 1, further comprising determining during the testing of the ~~contacting~~ electrical coupling between

the carrier and the semiconductor ~~chip~~ device whether a respective ~~electric~~ electrical contact has been established between a plurality of ~~pads~~ test contacts of the semiconductor ~~chip~~ device and respectively assigned pads of the carrier after loading of the carrier with the semiconductor ~~chip.~~ device.

10. (Currently Amended) The testing method according to claim 8, wherein power of current flowing through the ~~corresponding~~ test contact of the semiconductor ~~chip pad~~ device is determined to find whether [[an]] ~~electric~~ electrical contact has been established between [[a]] the test ~~corresponding pad~~ contact of the semiconductor ~~chip~~ device and [[an]] the assigned pad of the carrier.

11. (Currently Amended) The testing method according to claim 8, wherein an amount of voltage dropping across the corresponding semiconductor ~~chip pad~~ device contact is determined to find whether [[an]] ~~electric~~ electrical contact has been established between [[a]] the test ~~corresponding pad~~ contact of the semiconductor ~~chip~~ device and [[an]] the assigned pad of the carrier.

12.-14. (Canceled)

15. (Currently Amended) The method according to claim 1, wherein the one or more ~~contacting~~ exclusive test contacts are not used during ordinary operation of the semiconductor ~~chip.~~ device.

16. (Currently Amended) The method according to claim [[15,]] 1, wherein the semiconductor ~~chip~~ device further comprises at least one additional contact used during ordinary operation of the semiconductor ~~chip~~ device but not during testing.

17. (Currently Amended) The method according to claim 1, wherein the one or more ~~contacting~~ exclusive test contacts are not used for testing the functioning of the semiconductor ~~chip.~~ device.

18. (Currently Amended) The method according to claim 17, wherein the semiconductor ~~chip~~ device further comprises at least one additional contact used for testing the functioning of the semiconductor ~~chip.~~ device.

19.-22. (Canceled)

23. (Currently Amended) The testing method according to claim 1, wherein the one or more ~~contacting~~ exclusive test contacts are provided on a bottom of the semiconductor ~~chip.~~ device.

24. (Canceled)

25. (Previously Presented) The testing method according to claim 1, wherein the test carrier is a TSOP test carrier.

26.-29. (Canceled)

30. (New) A testing system for testing a semiconductor device comprising:

a carrier for transporting the semiconductor device;

a loader to load the semiconductor device adjacent the carrier, wherein the loading forms a contact between the semiconductor device and the carrier;

a contact tester electrically contacting the carrier, wherein the contact tester tests electrical coupling of the semiconductor device with the carrier, wherein the test

determines good or defective contacts, and

a functional tester physically separated from the contact tester, wherein the functional tester tests an electrical functionality of semiconductor devices with good contacts.

31. (New) The testing system of claim 30, wherein the loader unloads semiconductor devices with defective contacts.

32. (New) The testing system of claim 30, wherein the functional tester uses a "burn-in" test to test the electrical functionality of the semiconductor device.

33. (New) The testing system of claim 30, wherein the semiconductor device electrically couples to the carrier by directly contacting semiconductor device contacts with corresponding contacts on the carrier.

34. (New) The testing system of claim 30, further comprising a carrier adapter, wherein the carrier is electrically connected to the contact tester via the carrier adapter.

35. (New) A testing system that sequentially tests semiconductor devices, wherein a test is performed on each semiconductor device by the testing system, and wherein each test comprises:

loading the semiconductor device inside a carrier;

measuring electrical connectivity between the semiconductor device and the carrier;

identifying semiconductor devices with defective connections based on the

measurement; and

unloading semiconductor devices with defective connections from the carrier.

36. (New) The testing system of claim 35, wherein the semiconductor device comprises additional contacts used only by the testing system.

37. (New) The testing system of claim 35, wherein the semiconductor device without defective connections is passed onto a functional tester, wherein the functional tester tests the electrical functionality of the semiconductor device.

38. (New) The testing system of claim 37, wherein the functional tester uses a "burn-in" test to test the electrical functionality of the semiconductor device.

39. (New) The testing system of claim 35, wherein the testing system does not test the electrical functionality of the semiconductor device.